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# Electrical Characterization of Vertically Stacked p-FET SOI Nanowires

Bruna Cardoso Paz<sup>1</sup>, Mikael Cassé<sup>2</sup>, Sylvain Barraud<sup>2</sup>, Gilles Reibold<sup>2</sup>, Maud Vinet<sup>2</sup>, Olivier Faynot<sup>2</sup>  
and Marcelo Antonio Pavanello<sup>1</sup>

<sup>1</sup>Department of Electrical Engineering, Centro Universitário FEI, São Bernardo do Campo, Brazil

<sup>2</sup>Département des Composants Silicium – SCME/LCTE, CEA-LETI Minatec, Grenoble, France

bcpaz@fei.edu.br

**Abstract**—This work presents the performance and transport characteristics of vertically stacked p-type MOSFET SOI nanowires (NWs) with inner spacers and epitaxial growth of SiGe raised source/drain. The conventional procedure to extract the effective oxide thickness (EOT) and Shift and Ratio Method (S&R) have been adapted and validated through tridimensional numerical simulations. Electrical characterization is performed for NWs with [110]- and [100]-oriented channels, as a function of both fin width ( $W_{\text{FIN}}$ ) and channel length (L). Results show a good electrostatic control and reduced short channel effects (SCE) down to 15 nm gate length, for both orientations. Effective mobility is found around two times higher for [110]- in comparison to [100]-oriented NWs due to higher holes mobility contribution in (110) plan. Improvements obtained on  $I_{\text{ON}}/I_{\text{OFF}}$  by reducing  $W_{\text{FIN}}$  are mainly due to subthreshold slope decrease, once small and none mobility increase is obtained for [110]- and [100]-oriented NWs, respectively.

**Keywords**—performance; transport; electrical characterization; vertically stacked nanowire; SOI MOSFET; channel orientation

## I. INTRODUCTION

Once increasing the number of gates results in stronger immunity against short channel effects due to higher electrostatic coupling, triple gate (3G) and Gate-All-Around (GAA) MOSFETs attracted the interest of both scientific community and semiconductor industry [1]–[3]. Multiple gate MOSFETs with nanoscale silicon thickness and fin width, also called nanowires, have shown great performance and scalability, turning into one of the best candidates for future technological nodes [2], [4]. In these devices the silicon film thickness and the fin width are of the same order of magnitude.

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